insyde®

Investor Update

Insyde Software Corp.

Aug. 15 2022

Agenda

- **About Insyde**
- **Product Portfolio**
- **Financial Review & Company Updates**
- **Q&A**

About Insyde®

Insyde Software

6231.tw

- Founded in 1998 by PCT Chairman Jeremy Wang and SystemSoft EVP Jonathan Joseph
- Business started via acquisition of SystemSoft's BIOS division
- IPO January 23, 2003 (6231.TWO)
- Headquarters: Taipei, Taiwan
  - Major US operations in Massachusetts and Oregon
  - Other offices in Japan, China, Taichung (Taiwan)
  - Representatives in Europe

- UEFI Technology Leader
- Systems Manageability Provider

Worldwide Presence

Portland, USA

Boston, USA

Europe

Kunshan, China

Shanghai & Hangzhou, China

Beijing, China

Austin, USA

Tokyo, Japan

Shenzhen, China

Taipei, Taiwan(HQ)

Taichung, Taiwan

Insyde Office

Agent

BIOS – "Firmware"

BIOS is stored in the Flash memory and mounted on the motherboard

透過InsydeH2O 能有效率的協助產品的開發

CPU Register

80 Port

C Code window

Disassembly

Variable Window

Command Line

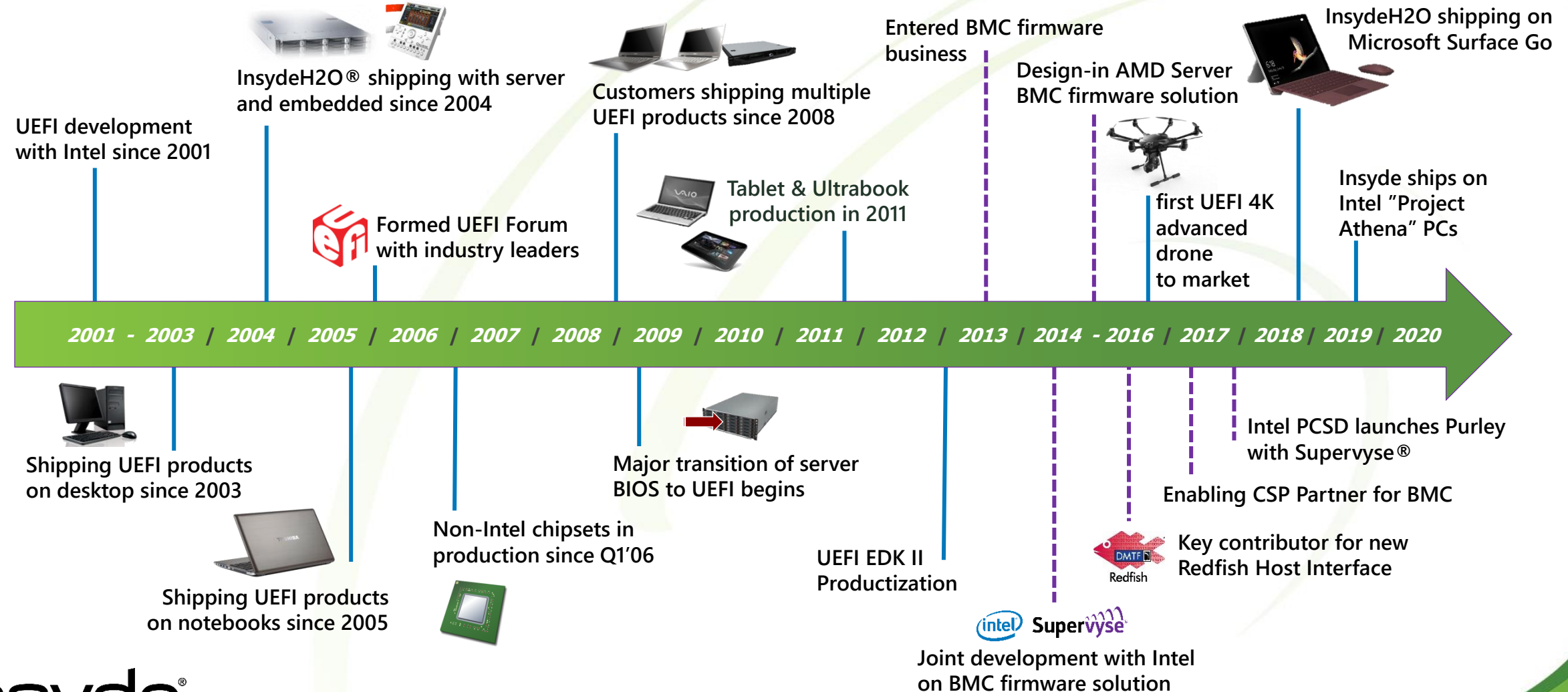# UEFI Forum (Unified Extensible Firmware Interface Forum)

- Original EFI specification developed by Intel, 1999 – 2001
- Specification taken over by non-profit, collaborative trade organization in 2005 – **UEFI Forum** (_http://www.uefi.org_)

  - Insyde is one of the 9 "Original Promoters", the only promoter from Taiwan
    - 11 Promoters now
      - **AMD, Intel, Microsoft, Dell, HP, IBM, Lenovo, AMI, Insyde, Phoenix, Apple, ARM**
    - 45 Contributors
      - **Google, NVIDIA, Qualcomm, Broadcom, Oracle, Cisco, Red Hat, Linaro, VMware, Linux Foundation**,….., etc.
    - More than 200 Adopters

Technology Leadership

Over 18+ Years of Industry-First Milestones and Leadership

InsydeH2O shipping on Microsoft Surface Go

Entered BMC firmware business

Design-in AMD Server BMC firmware solution

InsydeH2O® shipping with server and embedded since 2004

Customers shipping multiple UEFI products since 2008

UEFI development with Intel since 2001

Tablet & Ultrabook production in 2011

first UEFI 4K advanced drone to market

Insyde ships on Intel "Project Athena" PCs

Formed UEFI Forum with industry leaders

2001 - 2003 | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 - 2016 | 2017 | 2018 | 2019 | 2020

Shipping UEFI products on desktop since 2003

Major transition of server BIOS to UEFI begins

Intel PCSD launches Purley with Supervyse®

Enabling CSP Partner for BMC

Non-Intel chipsets in production since Q1'06

UEFI EDK II Productization

Key contributor for new Redfish Host Interface

Redfish

Shipping UEFI products on notebooks since 2005

intel Supervyse

Joint development with Intel on BMC firmware solution

insyde®

Trusted Supplier to Many Leading Companies

系微與高通攜手合作加速推動驍龍(Snapdragon) 5G筆記型電腦生態系統

系微將啟用UEFI韌體的專業技術與經驗擴展到高通驍龍(Snapdragon®)運算平台開發

2021年11月16日,台灣台北訊 - 系微股份有限公司,擁有BIOS最先進韌體運算技術(UEFI)及提供系統管理軟體的領導品牌,今日宣布與高通(Qualcomm)攜手合作加速推動搭載高通驍龍(Snapdragon®) 8cx 5G運算平台的5G筆記型電腦開發。

驍龍(Snapdragon) 8cx 5G運算平台已搭載於市面上多款功能強大、高效能兼安全的超輕便型個人電腦,透過提供長天期電池續航、千兆位元高速連網、企業等級資安防護以及AI加速等技術,能夠為個人電腦用戶實現常時連網、即時運算及通訊的最佳體驗。

今日合作奠基於系微在協助客戶產品設計、開發及生產個人電腦各方面的豐富經驗。系微與高通合作是搭載高通第一代及第二代驍龍(Snapdragon) 8cx 5G運算平台筆電成功上市的關鍵因素。系微的韌體解決方案為客戶提供多項關鍵整合服務與功能,包括協助ARM平台導入傳統x86生產製造流程、導入Setup Utility、為週邊裝置提供彈性的初始化程序以及為外部零組件之間的溝通提供客製化BIOS介面。

系微個人電腦事業群資深處長羅文華先生表示:「我們很高興能與高通合作持續協助個人電腦製造商推出新一波智能化、功能強大且可支援常時連網的個人電腦產品。」羅先生更進一步提及:「我們承諾全力與高通合作,也證明系微在協助客戶導入尖端運算解決方案上的領導地位。」

高通產品管理部處長Paul Hwang先生表示:「系微已成功建立驍龍(Snapdragon)筆電設計及開發關鍵推動者的地位。」Paul Hwang先生更進一步提及:「我們期待看到更多公司能藉助他們的專業技術與服務,持續為消費者、企業及教育市場提供更多具有卓越性能、高效能及5G連網體驗的驍龍(Snapdragon)運算平台個人電腦新產品。」

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英特爾、系微、臺北大學UEFI韌體人才培訓課程

銜接高等教育與業界實作 培養世界級UEFI韌體開發未來人才

【2022年7月12日】-英特爾、系微攜手國立臺北大學，開設並已完成首期UEFI韌體開發人才培訓課程！此培訓課程由系微負責課程規劃與教材內容、英特爾提供搭載Intel® Core™處理器的硬體平台，於臺北大學首次推出，幫助有興趣的大學生清楚了解UEFI韌體介面如何與今日電腦架構互動，同時也為台灣強健資通訊產業播下更多韌體人才種子，善盡企業社會責任。

UEFI（Unified Extensible Firmware Interface，統一可延伸韌體介面）已在普遍所使用的x86架構電腦當中取代傳統BIOS（Basic Input/Output System，基本輸入輸出系統），負責在開機時初始化硬體，並作為硬體、韌體和作業系統中間的溝通介面。UEFI有著許多特色與優勢，包含執行於32位元/64位元模式，而非記憶體容量受限的BIOS 16位元真實模式，以及支援安全開機功能等。UEFI使用C語言並導入模組化概念，對於開發者而言更易於修改與發展獨有特色，如目前各個主機板廠牌的圖形化UEFI介面即為範例之一。

硬體需要設計完善的韌體和軟體，始能將整體效能發揮得淋漓盡致，幾乎每樣電子產品均需要韌體才能運作，例如日常生活經常使用的USB充電器和行動電源，內部設有韌體處理充放電作業與安全保護機制。韌體開發可適用於所有產品，UEFI開發工作尤其核心。台灣資通訊產業發達，UEFI人才需求活絡，英特爾作為全球產業領導企業，希望協助學生接軌產業，並以容易取得相關資源的MinPlatform開放原始碼進行個人電腦/伺服器UEFI開發，讓更多優秀人才可以輕鬆地投入研究，並計畫提供實習機會給具備相關經驗與實力的新鮮人。

英特爾台灣分公司總經理劉景慈表示：「英特爾在全球各國有不同層面的人才培育計畫。這次在台灣很高興能夠和系微合作，為臺北大學的學生提供培訓課程，透過此次三方產學合作，不僅強化學子對韌體的興趣及教育，也協助大專院校銜接業界需求，相信未來更有機會為整個產業帶來豐富的人才。」

英特爾和系微皆為UEFI論壇的創始者暨推廣者會員之一，在UEFI方面皆有深厚的底蘊。系微更是唯一總部設在台灣的UEFI解決方案供應商，極為重視UEFI在台灣日後的發展，期盼以這次三方合作擴大影響未來人才庫的質與量。系微除提供業界教學師資之外，還貢獻教材內容，不藏私地將自行開發的H2ODDT系統診斷與除錯工具供教學使用。學生、開發者僅透過一條USB連結線即可得知開發平台的運作狀況，取代傳統使用昂貴硬體拉線至開發平台的方式，大幅度降低入門門檻與開發時間。

系微總經理莊鈴文表示：「我們觀察到越來越多的客戶與合作夥伴有更多UEFI工程師需求。系微很榮幸多年來透過產學合作，有機會讓學生深入了解這個領域相關的就業選擇，將他們在技術的興趣轉換成系統韌體方面的職涯成就。與臺北大學合作之課程強調實作技巧，這對於培育具備創新思維、世界級的下一代UEFI工程師相當重要，希望台灣也能夠有更多夥伴加入，一起培養更多UEFI人才。」

這門UEFI培訓課程開設在甫圓滿結束的臺北大學資訊工程學系四年級110學年度第二學期，吸引34位學生報名選修，甚至還有已搶先修習完畢程式設計、資料結構、演算法等必修課程的大二、大三學生，以及外系學生加入。資訊工程系所過去較為深入介紹作業系統和應用程式，底層硬體互動相對缺乏，此課程讓學生理解職場需求，未來應用所學銜接職場將更為順暢。課程經過18週教學，不僅將學校的基礎教育、學術養成結合實作與業界應用，通過課堂標準的學生亦可獲得3學分，並且獲得珍貴的專案開發經驗。

臺北大學資訊工程學系教授張仁俊表示：「系微和英特爾所提供的培訓課程讓學生有很好的機會接觸UEFI架構，並擁有開發軟體與驅動程式的實際經驗。學生透過參加這門與業界接軌的課程，不僅能夠增加實作經驗優勢，更可熟稔這個前景無限的職涯領域。」

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Product Portfolio

產品之市場應用

Client Computing
Notebook, Tablet, AIO, and Desktop

Server & Storage
Data Center, Enterprise Server Storage, and Networking

Embedded & IoT
POS, Drone, Kiosk, ATM, Robot , Car system..

Next-Generation Intel Evo Certified Notebooks are Powered by InsydeH2O

**Dell Latitude 9420 & 9520
2-in-1 Laptops**

**Acer Porsche Design RS
& Swift 5**

HP Envy 13

**Lenovo Yoga Slim
(9i, 7i Pro, & 7i Carbon)**

- Intel Evo platform was certified with Project Athena Spec v2 & KEI (Key Experience Index)
- InsydeH2O® helps OEMs and ODMs meet stringent requirements for shipping the industry's most innovative high performance, Intel Evo-certified PCs
- Featuring the 11th Generation Intel® Core® i7 or i5 processors and Iris Xe graphics
- WiFi 6, Thunderbolt 4, instant wake and 9+ hours battery life

Insyde Powers Innovation PCs Featuring AMD Ryzen™ 5000 Series Mobile Processors

Acer Nitro 5 Gaming

Alienware M15 R5 Gaming

Fujitsu LIFEBOOK AH Series

HP Envy x360 Convertible

Lenovo Legion 5 & 5 Pro Gaming

- Latest AMD Ryzen 5000 Series Mobile Processors leveraging TSMC 7nm process
- Integrated NVIDIA & AMD Graphics to bring incredible performance for work and play
- Supports WiFi 6 & Bluetooth 5.1/5.2 technology for speedy connection
- Microsoft Modern Standby support for instant responsiveness

Insyde Powers ARM-based 5G Windows Laptops

HP Elite Folio Convertible

- Qualcomm Snapdragon 8cx Gen 2 Compute Platform
- Features Snapdragon X20 & X55 modem, supporting both 4G LTE and 5G networks

Acer Spin 7 5G Convertible

- Qualcomm Snapdragon 8cx Gen 2 Compute Platform
- Supports 5G across both mmWave and sub-6 GHz frequencies
- Up to 29 hours battery life

Lenovo Yoga 5G 2-in-1

- The world's first 5G PC to market
- Qualcomm Snapdragon 8cx Compute Platform
- Supports 5G and up to 24 hours battery life
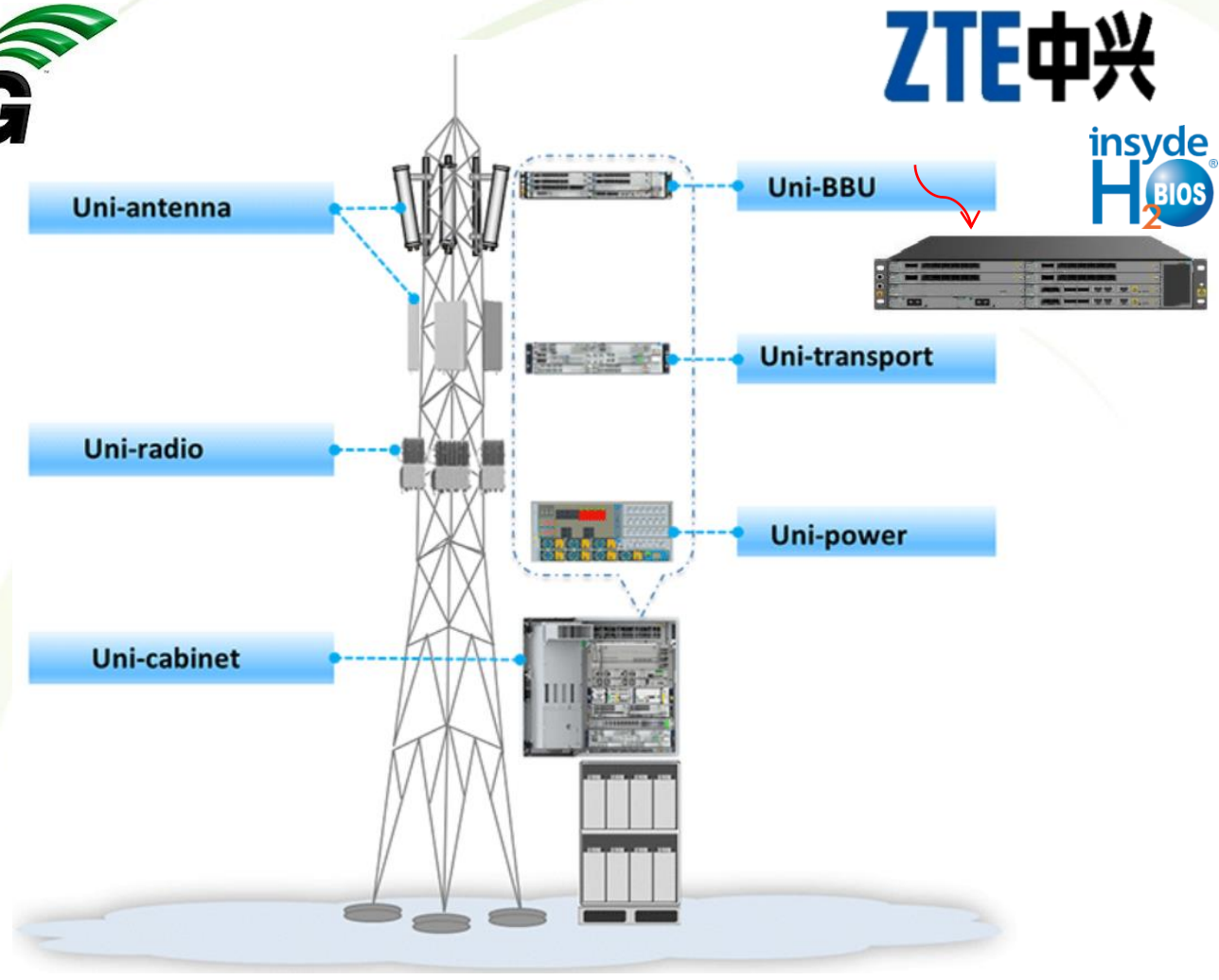
Customer Product Highlights

5G Baseband 6648

- Powered by InsydeH2O® UEFI BIOS

- Designed for 4G and 5G high-capacity sites with 10-15 Gbps maximum downlink throughput

- Featuring Intel® Atom™ P5000 Series Processors (formerly Snow Ridge)

Customer Product Highlights

FusionServer Pro 1288H/2288H V6 Rack Server

Powered by InsydeH2O® UEFI BIOS

- The 1288H V6 is configured with two Intel® Xeon® Scalable processors and provides up to 32 DDR4 DIMMs, and 4 x 3.5-inch or 10 x 2.5-inch local storage resources

- Featuring One or two 3rd Gen Intel® Xeon® Scalable Ice Lake processors

R5300 G4X 双路2U架式服务器

Powered by InsydeH2O® UEFI BIOS

- R5300 G4X is a new generation 2U2 general rack server and supporting two Intel ® Xeon ® third generation extensible processors (Ice Lake).

- R5300 G4X is designed with high density, modularization and streamline. It features high performance, high reliability, easy scalability and easy management, which is widely applicable to Internet, cloud computing, big data and NFV.

Customer Product Highlights

QuantaGrid D53X-1U (Rackmount Server)

- Powered & Managed by InsydeH2O® UEFI BIOS & Supervyse ® BMC Firmware

- System optimized for cloud, enterprise, AI, HPC, network, security and IoT workloads

- Featuring 3rd Gen Intel® Xeon® Scalable processor (Ice Lake SP) with improved security technology: Intel® SGX, Intel® Crypto Acceleration and PFR

Trenton Systems 3U BAM Server

- Powered & by InsydeH2O® UEFI BIOS

- High-performance rugged server designed for industrial edge and military

- Featuring 3rd Gen Intel® Xeon® Scalable processor (Ice Lake SP) with improved security technology: Intel® SGX, Intel® Crypto Acceleration and PFR

Financial Review & Company Update

insyde®

Annual Consolidated Income Statement

In NT$ Thousands	Q2'22	Q1'22	Q2'21	QoQ%	YoY%
Net Sales	344,361	356,989	306,206	-3.54	12.46
COGS	59,458	50,134	65,162	18.60	-8.75
Gross Profit	284,903	306,855	241,044	-7.15	18.20
Gross margin	82.73%	85.96%	78.72%		
Operating Expense	202,354	215,305	183,957	-6.02	10.00
Operating Income	82,549	91,550	57,087	-9.83	44.60
Operation Margin	23.97%	25.65%	18.64%		
Non-Op Inc/(Exp)	9,121	6,358	(1,009)	43.46	1,003.96
Income before Tax	91,670	97,908	56,078	-6.37	63.47
Net Income	71,560	73,460	39,225	-2.60	82.43
Net Margin	20.78%	20.58%	12.81%		
EPS	1.88	1.93	1.03		

*Accumulated year-to date EPS is NT$ 3.81

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Consolidated Balance Sheet Summary

Selected Items from Balance Sheet (NT$ Millions)	Q2'22		Q1'22		Q2'21	
	Amount	%	Amount	%	Amount	%
Current Assets	1,322.8	90.5%	1,212.0	88.7%	1,137.8	88.7%
Fixed Assets	33.6	2.3%	36.1	2.6%	23.6	1.8%
Net PP&E and other assets	105.8	7.2%	118.3	8.7%	120.9	9.5%
Total Assets	1,462.2	100.0%	1,366.4	100.0%	1,282.3	100.0%
Current Liabilities	600.7	41.1%	374.4	27.4%	390.0	30.4%
Non Current Liabilities	46.7	3.2%	58.5	4.3%	68.2	5.3%
Total Liabilities	647.4	44.3%	432.9	31.7%	458.2	35.7%
Shareholders' Equity	814.8	55.7%	933.5	68.3%	824.1	64.3%

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